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| NP505-LT      | Sn42Bi57Ag1        | Jar, Cartridge          | ▪ This no-clean, low temperature paste reduces mismatch of CTEs between components and boards.  
▪ Low temperature paste uses Sn42Bi57Ag1 T4 powder, which has a melt point temperature of 138°C. |
| NP560         | SAC305             | Jar, Cartridge, Syringe | ▪ No-Clean, Halogen-Free  
▪ Low voiding under QFNs <5% consistently  
▪ Colorless residues for easy post-reflow inspection |
| WP616         | SAC305             | Jar, Cartridge          | ▪ Water-soluble, Zero-Halogen  
▪ Designed for improved compatibility with T4 powder |
| NP545         | SAC305, SnPb       | Jar, Cartridge          | ▪ No-clean, Zero-Halogen  
▪ 12-month room temperature shelf-life that has shown use of ease for customers in high mix, low volume type of manufacturing.  
▪ Fine pitch release remains consistent from speeds of 1-8 in/sec  
▪ The in-circuit probe testing result exceeded the IPC-HDBK-005 recommended acceptable standard for a 1.8 oz probe force |
| NP505-HR      | SAC305             | Jar, Cartridge          | ▪ No-Clean, Zero-Halogen  
▪ High reliability – great for products used in harsh environmental conditions including medical, military and industrial  
▪ Compatible with multiple conformal coatings |

SAC305 T5 powder is now available with NP545, NP560 and WP616 solder pastes (previously was only available with NP505-HR). The Data Sheets have been updated to reflect this addition.

High Reliability/Performance Alloy K328-HP has moved on to Phase 2 of an evaluation at a leading global automotive emissions, fuel economy and aftermarket solutions provider.

**RS20A:** A service leader in the electronic interconnect industry and a global manufacturer of Connectors, Cables, Optics and RF Systems is evaluating RS20A Solder Paste (SAC305, T3).